External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.47604	100.0	1.1
			Subtotal	0.47604	100	1.1
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.59242	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
			Subtotal	1.59258	100	3.68
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01199	0.03	0.02772
	Copper alloy	Iron (Fe)	7439-89-6	0.03998	0.1	0.09239
	Copper alloy	Copper (Cu)	7440-50-8	39.82328	99.6	92.02044
	Pure metal layer	Silver (Ag)	7440-22-4	0.10795	0.27	0.24945
			Subtotal	39.9832	100	92.39
Adhesive	Polymer	Paraffin wax	8002-74-2	0.18522	20.0	0.428
	Polymer	Epoxy resin system		0.07409	8.0	0.1712
	Filler	Silver (Ag)	7440-22-4	0.66681	72.0	1.5408
			Subtotal	0.92612	100	2.14
Mould Compound	Flame retardant	Zinc Borate	138265-88-0	2.54237	4.46	5.87471
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.13035	9.0	11.8548
	Filler	Silica -amorphous-	7631-86-9	17.6712	31.0	40.8332
	Pigment	Carbon black	1333-86-4	0.30782	0.54	0.71129
	Filler	Silicon Dioxide (SiO2)	14808-60-7	31.35213	55.0	72.446
			Subtotal	57.00387	100	131.72
Wire	Copper alloy	Copper (Cu)	7440-50-8	0.01818	100.0	0.042
			Subtotal	0.01818	100	0.042
			Total	99.99999	100	231.072

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